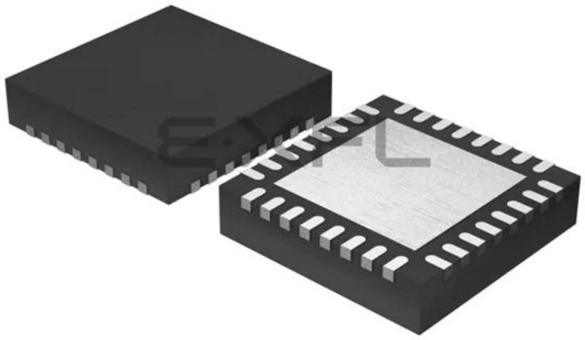

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	20
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.85V ~ 3.8V
Data Converters	A/D 24x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32jg1b100f128gm32-c0

4.1.5 Current Consumption

4.1.5.1 Current Consumption 3.3 V without DC-DC Converter

Unless otherwise indicated, typical conditions are: VREGVDD = AVDD = DVDD = 3.3 V. T_{OP} = 25 °C. EMU_PWRCFG_PWRCG=NODCDC. EMU_DCDCCTRL_DCDCMODE=BYPASS. Minimum and maximum values in this table represent the worst conditions across supply voltage and process variation at T_{OP} = 25 °C. See Figure 5.1 EFM32JG1 Typical Application Circuit, Direct Supply, No DC-DC Converter on page 48.

Table 4.5. Current Consumption 3.3V without DC/DC

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 Active mode with all peripherals disabled	I_{ACTIVE}	38.4 MHz crystal, CPU running while loop from flash[1]	—	127	—	μA/MHz
		38 MHz HFRCO, CPU running Prime from flash	—	88	—	μA/MHz
		38 MHz HFRCO, CPU running while loop from flash	—	100	105	μA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	—	112	—	μA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	102	106	μA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	222	350	μA/MHz
Current consumption in EM1 Sleep mode with all peripherals disabled	I_{EM1}	38.4 MHz crystal[1]	—	61	—	μA/MHz
		38 MHz HFRCO	—	35	38	μA/MHz
		26 MHz HFRCO	—	37	41	μA/MHz
		1 MHz HFRCO	—	157	275	μA/MHz
Current consumption in EM2 Deep Sleep mode.	I_{EM2}	Full RAM retention and RTCC running from LFXO	—	3.3	—	μA
		4 kB RAM retention and RTCC running from LFRCO	—	3	6.3	μA
Current consumption in EM3 Stop mode	I_{EM3}	Full RAM retention and CRYOTIMER running from ULFRCO	—	2.8	6	μA
Current consumption in EM4H Hibernate mode	I_{EM4}	128 byte RAM retention, RTCC running from LFXO	—	1.1	—	μA
		128 byte RAM retention, CRYOTIMER running from ULFRCO	—	0.65	—	μA
		128 byte RAM retention, no RTCC	—	0.65	1.3	μA
Current consumption in EM4S Shutoff mode	I_{EM4S}	no RAM retention, no RTCC	—	0.04	0.11	μA

Note:

1. CMU_HFXOCTRL_LOWPOWER=1

4.1.5.2 Current Consumption 3.3 V using DC-DC Converter

Unless otherwise indicated, typical conditions are: VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = 1.8 V DC-DC output. T_{OP} = 25 °C. Minimum and maximum values in this table represent the worst conditions across supply voltage and process variation at T_{OP} = 25 °C. See Figure 5.2 EFM32JG1 Typical Application Circuit Using the DC-DC Converter on page 48.

Table 4.6. Current Consumption 3.3V with DC-DC

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 Active mode with all peripherals disabled, DCDC in Low Noise DCM mode[1].	I_{ACTIVE}	38.4 MHz crystal, CPU running while loop from flash[2]	—	86	—	µA/MHz
		38 MHz HFRCO, CPU running Prime from flash	—	63	—	µA/MHz
		38 MHz HFRCO, CPU running while loop from flash	—	71	—	µA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	—	78	—	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	76	—	µA/MHz
Current consumption in EM0 Active mode with all peripherals disabled, DCDC in Low Noise CCM mode[3].		38.4 MHz crystal, CPU running while loop from flash[2]	—	96	—	µA/MHz
		38 MHz HFRCO, CPU running Prime from flash	—	75	—	µA/MHz
		38 MHz HFRCO, CPU running while loop from flash	—	81	—	µA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	—	88	—	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	94	—	µA/MHz
Current consumption in EM1 Sleep mode with all peripherals disabled, DCDC in Low Noise DCM mode[1].	I_{EM1}	38.4 MHz crystal[2]	—	47	—	µA/MHz
		38 MHz HFRCO	—	32	—	µA/MHz
		26 MHz HFRCO	—	38	—	µA/MHz
Current consumption in EM1 Sleep mode with all peripherals disabled, DCDC in Low Noise CCM mode[3].		38.4 MHz crystal[2]	—	59	—	µA/MHz
		38 MHz HFRCO	—	45	—	µA/MHz
		26 MHz HFRCO	—	58	—	µA/MHz
Current consumption in EM2 Deep Sleep mode. DCDC in Low Power mode[4].	I_{EM2}	Full RAM retention and RTCC running from LFXO	—	2.5	—	µA
		4 kB RAM retention and RTCC running from LFRCO	—	2.2	—	µA
Current consumption in EM3 Stop mode	I_{EM3}	Full RAM retention and CRYOTIMER running from ULFRCO	—	2.1	—	µA
Current consumption in EM4H Hibernate mode	I_{EM4}	128 byte RAM retention, RTCC running from LFXO	—	0.86	—	µA
		128 byte RAM retention, CRYOTIMER running from ULFRCO	—	0.58	—	µA
		128 byte RAM retention, no RTCC	—	0.58	—	µA

4.1.9 Flash Memory Characteristics

Table 4.15. Flash Memory Characteristics[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC_{FLASH}		10000	—	—	cycles
Flash data retention	RET_{FLASH}	$T_{AMB} \leq 85$ °C	10	—	—	years
		$T_{AMB} \leq 125$ °C	10	—	—	years
Word (32-bit) programming time	t_{W_PROG}		20	26	40	µs
Page erase time	t_{PERASE}		20	27	40	ms
Mass erase time	t_{MERASE}		20	27	40	ms
Device erase time[2]	t_{DERASE}	$T_{AMB} \leq 85$ °C	—	60	74	ms
		$T_{AMB} \leq 125$ °C	—	60	78	ms
Page erase current[3]	I_{ERASE}		—	—	3	mA
Mass or Device erase current[3]			—	—	5	mA
Write current[3]	I_{WRITE}		—	—	3	mA

Note:

1. Flash data retention information is published in the Quarterly Quality and Reliability Report.
2. Device erase is issued over the AAP interface and erases all flash, SRAM, the Lock Bit (LB) page, and the User data page Lock Word (ULW)
3. Measured at 25°C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current from all supplies, using internal reference buffer. Duty-cycled operation. WARMUPMODE[2] = NORMAL	$I_{ADC\_NORMAL\_HP}$	35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 [3]	—	102	—	μA
		5 ksps / 16 MHz ADCCLK BIASPROG = 0, GPBIASACC = 0 [3]	—	17	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. AWARMUPMODE[2] = KEEPINSTANDBY or KEEPINSLOWACC	$I_{ADC\_STANDBY\_HP}$	125 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 [3]	—	162	—	μA
		35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 [3]	—	123	—	μA
Current from HFPERCLK	I_{ADC_CLK}	HFPERCLK = 16 MHz	—	140	—	μA
ADC Clock Frequency	f_{ADCCLK}		—	—	16	MHz
Throughput rate	$f_{ADCRATE}$		—	—	1	Msps
Conversion time[4]	$t_{ADCCONV}$	6 bit	—	7	—	cycles
		8 bit	—	9	—	cycles
		12 bit	—	13	—	cycles
Startup time of reference generator and ADC core	$t_{ADCSTART}$	WARMUPMODE[2] = NORMAL	—	—	5	μs
		WARMUPMODE[2] = KEEPINSTANDBY	—	—	2	μs
		WARMUPMODE[2] = KEEPINSLOWACC	—	—	1	μs
SNDR at 1Msps and f_{in} = 10kHz	$SNDR_{ADC}$	Internal reference, 2.5 V full-scale, differential (-1.25, 1.25)	58	67	—	dB
		vrefp_in = 1.25 V direct mode with 2.5 V full-scale, differential	—	68	—	dB
Spurious-Free Dynamic Range (SFDR)	$SFDR_{ADC}$	1 MSamples/s, 10 kHz full-scale sine wave	—	75	—	dB
Input referred ADC noise, rms	V_{REF_NOISE}	Including quantization noise and distortion	—	380	—	μV
Offset Error	$V_{ADCOFFSETERR}$		-3	0.25	3	LSB
Gain error in ADC	V_{ADC_GAIN}	Using internal reference	—	-0.2	5	%
		Using external reference	—	-1	—	%
Differential non-linearity (DNL)	DNL_{ADC}	12 bit resolution, No Missing Codes	-1	—	2	LSB
Integral non-linearity (INL), End point method	INL_{ADC}	12 bit resolution	-6	—	6	LSB
Temperature Sensor Slope	V_{TS_SLOPE}		—	-1.84	—	mV/°C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit

Note:

1. PSRR is referenced to AVDD when ANASW=0 and to DVDD when ANASW=1 in EMU_PWRCTRL
2. In ADCn_CNTL register
3. In ADCn_BIASPROG register
4. Derived from ADCCLK

I2C Fast-mode (Fm)

Table 4.22. I2C Fast-mode (Fm)[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency[2]	f_{SCL}		0	—	400	kHz
SCL clock low time	t_{LOW}		1.3	—	—	µs
SCL clock high time	t_{HIGH}		0.6	—	—	µs
SDA set-up time	$t_{SU,DAT}$		100	—	—	ns
SDA hold time[3]	$t_{HD,DAT}$		100	—	900	ns
Repeated START condition set-up time	$t_{SU,STA}$		0.6	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$		0.6	—	—	µs
STOP condition set-up time	$t_{SU,STO}$		0.6	—	—	µs
Bus free time between a STOP and START condition	t_{BUF}		1.3	—	—	µs

Note:

1. For CLHR set to 1 in the I2Cn_CTRL register
2. For the minimum HFPERCLK frequency required in Fast-mode, refer to the I2C chapter in the reference manual
3. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW})

I2C Fast-mode Plus (Fm+)

Table 4.23. I2C Fast-mode Plus (Fm+)[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency[2]	f_{SCL}		0	—	1000	kHz
SCL clock low time	t_{LOW}		0.5	—	—	µs
SCL clock high time	t_{HIGH}		0.26	—	—	µs
SDA set-up time	$t_{SU,DAT}$		50	—	—	ns
SDA hold time	$t_{HD,DAT}$		100	—	—	ns
Repeated START condition set-up time	$t_{SU,STA}$		0.26	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$		0.26	—	—	µs
STOP condition set-up time	$t_{SU,STO}$		0.26	—	—	µs
Bus free time between a STOP and START condition	t_{BUF}		0.5	—	—	µs

Note:
1. For CLHR set to 0 or 1 in the I2Cn_CTRL register
2. For the minimum HFPERCLK frequency required in Fast-mode Plus, refer to the I2C chapter in the reference manual

4.2.2 DC-DC Converter

Default test conditions: CCM mode, LDCDC = 4.7 µH, CDCDC = 1.0 µF, VDCDC_I = 3.3 V, VDCDC_O = 1.8 V, FDCDC_LN = 7 MHz

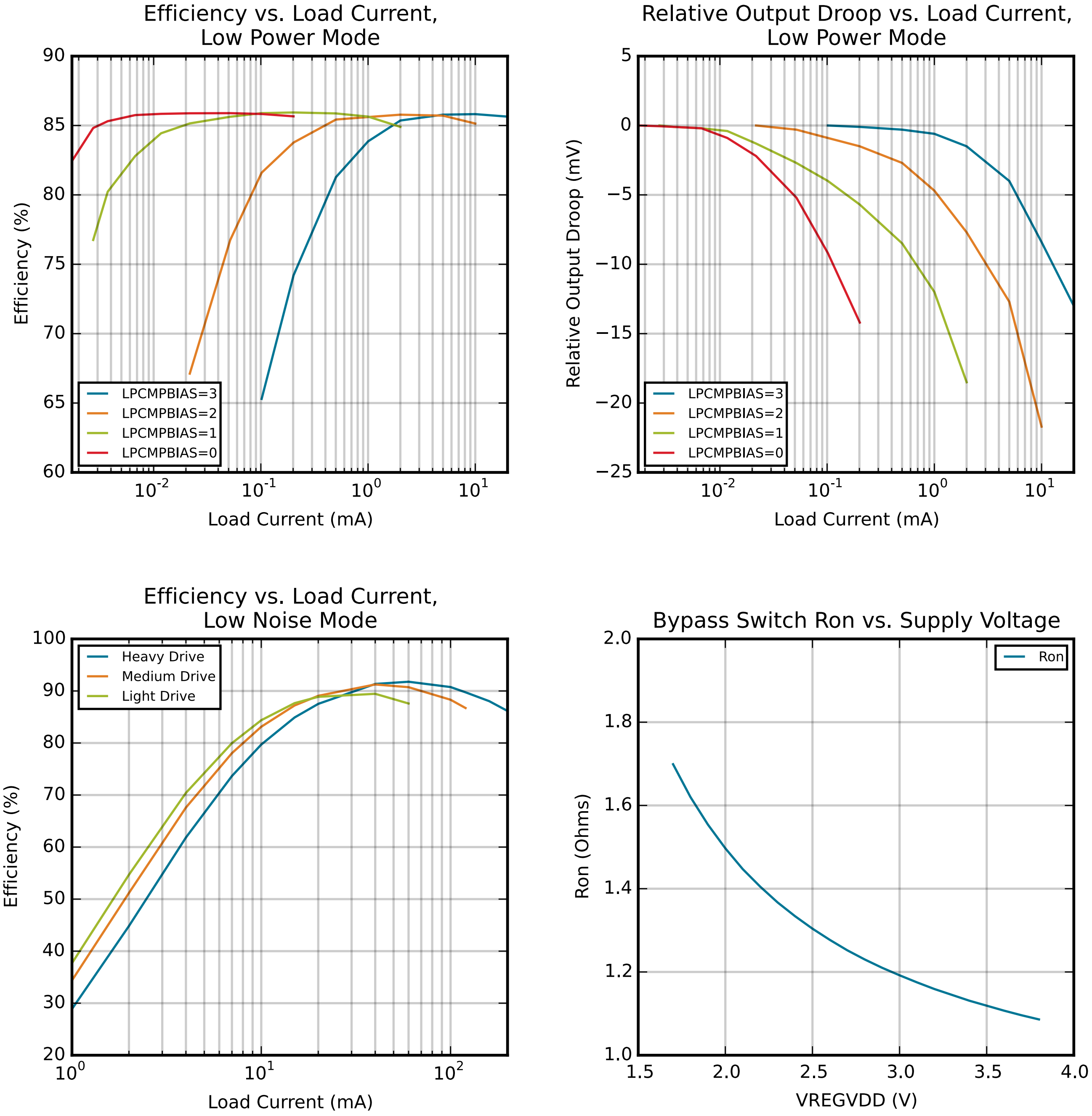

Figure 4.6. DC-DC Converter Typical Performance Characteristics

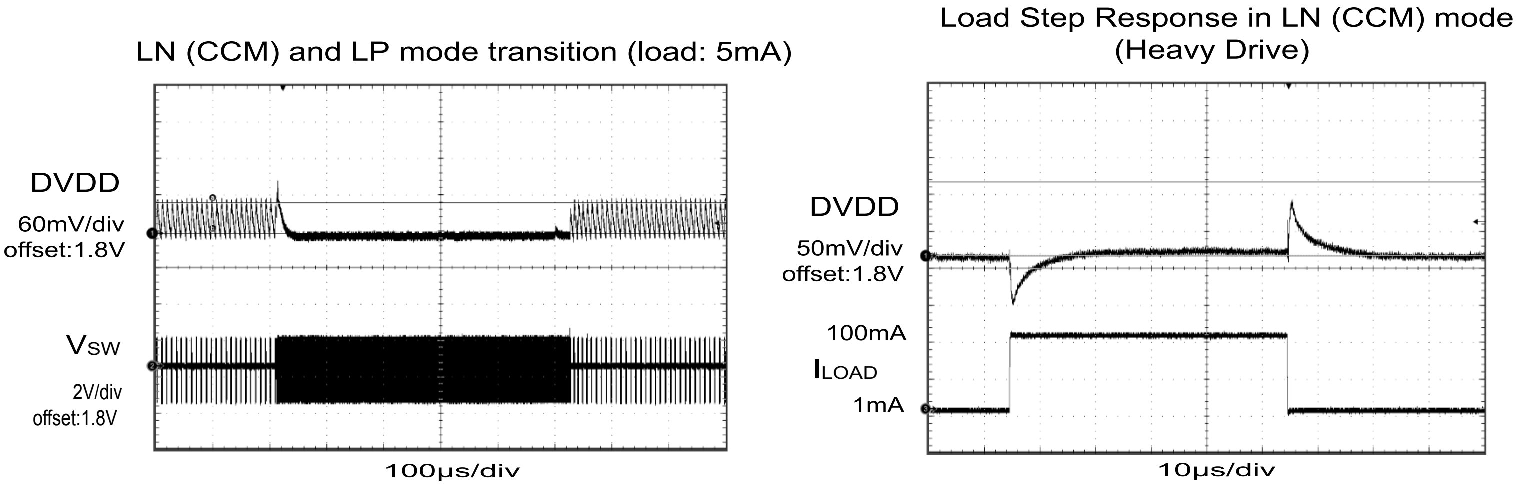

Figure 4.7. DC-DC Converter Transition Waveforms

5. Typical Connection Diagrams

5.1 Power

Typical power supply connections for direct supply, without using the internal dc-dc converter, are shown in Figure 5.1 EFM32JG1 Typical Application Circuit, Direct Supply, No DC-DC Converter on page 48.

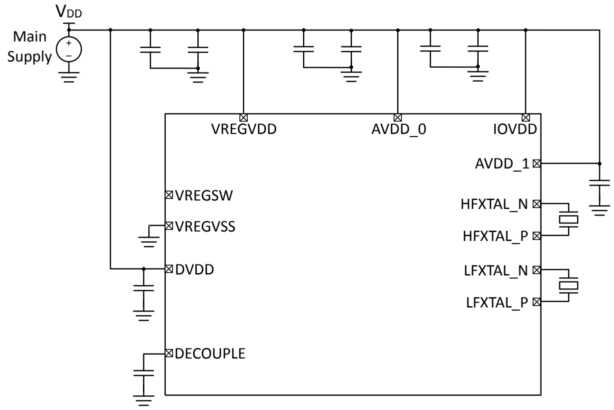

Figure 5.1. EFM32JG1 Typical Application Circuit, Direct Supply, No DC-DC Converter

A typical application circuit using the internal dc-dc converter is shown in Figure 5.2 EFM32JG1 Typical Application Circuit Using the DC-DC Converter on page 48. The MCU operates from the dc-dc converter supply.

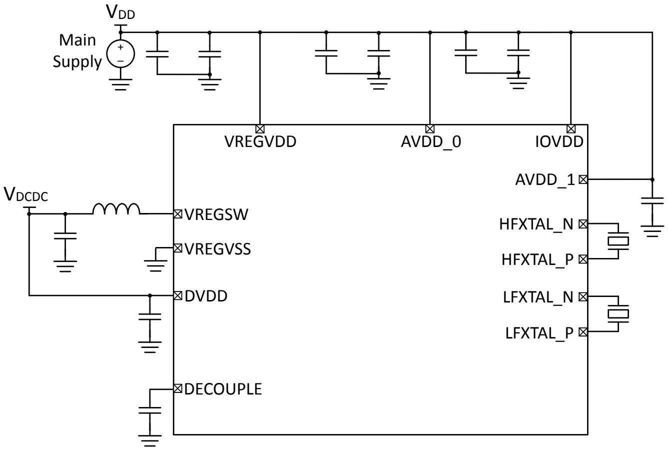

Figure 5.2. EFM32JG1 Typical Application Circuit Using the DC-DC Converter

5.2 Other Connections

Other components or connections may be required to meet the system-level requirements. Application Note AN0002: "Hardware Design Considerations" contains detailed information on these connections. Application Notes can be accessed on the Silicon Labs website (www.silabs.com/32bit-appnotes).

6.1.1 EFM32JG1 QFN48 with DC-DC GPIO Overview

The GPIO pins are organized as 16-bit ports indicated by letters (A, B, C...), and the individual pins on each port are indicated by a number from 15 down to 0.

Table 6.2. QFN48 with DC-DC GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	PA5 (5V)	PA4 (5V)	PA3 (5V)	PA2 (5V)	PA1	PA0
Port B	PB15	PB14	PB13 (5V)	PB12 (5V)	PB11 (5V)	-	-	-	-	-	-	-	-	-	-	-
Port C	-	-	-	-	PC11 (5V)	PC10 (5V)	PC9 (5V)	PC8 (5V)	PC7 (5V)	PC6 (5V)	-	-	-	-	-	-
Port D	PD15 (5V)	PD14 (5V)	PD13 (5V)	PD12 (5V)	PD11 (5V)	PD10 (5V)	PD9 (5V)	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	PF7 (5V)	PF6 (5V)	PF5 (5V)	PF4 (5V)	PF3 (5V)	PF2 (5V)	PF1 (5V)	PF0 (5V)

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PA4, PA3, PA2, PB13, PB12, PB11, PD15, PD14, and PD13 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
15	PD14	BUSCX BUSDY	TIM0_CC0 #22 TIM0_CC1 #21 TIM0_CC2 #20 TIM0_CDTI0 #19 TIM0_CDTI1 #18 TIM0_CDTI2 #17 TIM1_CC0 #22 TIM1_CC1 #21 TIM1_CC2 #20 TIM1_CC3 #19 LETIM0_OUT0 #22 LETIM0_OUT1 #21 PCNT0_S0IN #22 PCNT0_S1IN #21	US0_TX #22 US0_RX #21 US0_CLK #20 US0_CS #19 US0_CTS #18 US0_RTS #17 US1_TX #22 US1_RX #21 US1_CLK #20 US1_CS #19 US1_CTS #18 US1_RTS #17 LEU0_TX #22 LEU0_RX #21 I2C0_SDA #22 I2C0_SCL #21	CMU_CLK0 #5 PRS_CH3 #13 PRS_CH4 #5 PRS_CH5 #4 PRS_CH6 #16 ACMP0_O #22 ACMP1_O #22 GPIO_EM4WU4
16	PD15	BUSCY BUSDX	TIM0_CC0 #23 TIM0_CC1 #22 TIM0_CC2 #21 TIM0_CDTI0 #20 TIM0_CDTI1 #19 TIM0_CDTI2 #18 TIM1_CC0 #23 TIM1_CC1 #22 TIM1_CC2 #21 TIM1_CC3 #20 LETIM0_OUT0 #23 LETIM0_OUT1 #22 PCNT0_S0IN #23 PCNT0_S1IN #22	US0_TX #23 US0_RX #22 US0_CLK #21 US0_CS #20 US0_CTS #19 US0_RTS #18 US1_TX #23 US1_RX #22 US1_CLK #21 US1_CS #20 US1_CTS #19 US1_RTS #18 LEU0_TX #23 LEU0_RX #22 I2C0_SDA #23 I2C0_SCL #22	CMU_CLK1 #5 PRS_CH3 #14 PRS_CH4 #6 PRS_CH5 #5 PRS_CH6 #17 ACMP0_O #23 ACMP1_O #23 DBG_SWO #2
17	PA0	ADC0_EXTN BUSCX BUSDY	TIM0_CC0 #0 TIM0_CC1 #31 TIM0_CC2 #30 TIM0_CDTI0 #29 TIM0_CDTI1 #28 TIM0_CDTI2 #27 TIM1_CC0 #0 TIM1_CC1 #31 TIM1_CC2 #30 TIM1_CC3 #29 LETIM0_OUT0 #0 LETIM0_OUT1 #31 PCNT0_S0IN #0 PCNT0_S1IN #31	US0_TX #0 US0_RX #31 US0_CLK #30 US0_CS #29 US0_CTS #28 US0_RTS #27 US1_TX #0 US1_RX #31 US1_CLK #30 US1_CS #29 US1_CTS #28 US1_RTS #27 LEU0_TX #0 LEU0_RX #31 I2C0_SDA #0 I2C0_SCL #31	CMU_CLK1 #0 PRS_CH6 #0 PRS_CH7 #10 PRS_CH8 #9 PRS_CH9 #8 ACMP0_O #0 ACMP1_O #0
18	PA1	ADC0_EXTP BUSCY BUSDX	TIM0_CC0 #1 TIM0_CC1 #0 TIM0_CC2 #31 TIM0_CDTI0 #30 TIM0_CDTI1 #29 TIM0_CDTI2 #28 TIM1_CC0 #1 TIM1_CC1 #0 TIM1_CC2 #31 TIM1_CC3 #30 LETIM0_OUT0 #1 LETIM0_OUT1 #0 PCNT0_S0IN #1 PCNT0_S1IN #0	US0_TX #1 US0_RX #0 US0_CLK #31 US0_CS #30 US0_CTS #29 US0_RTS #28 US1_TX #1 US1_RX #0 US1_CLK #31 US1_CS #30 US1_CTS #29 US1_RTS #28 LEU0_TX #1 LEU0_RX #0 I2C0_SDA #1 I2C0_SCL #0	CMU_CLK0 #0 PRS_CH6 #1 PRS_CH7 #0 PRS_CH8 #10 PRS_CH9 #9 ACMP0_O #1 ACMP1_O #1

6.2.1 EFM32JG1 QFN32 without DC-DC GPIO Overview

The GPIO pins are organized as 16-bit ports indicated by letters (A, B, C...), and the individual pins on each port are indicated by a number from 15 down to 0.

Table 6.4. QFN32 without DC-DC GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	-	PA1	PA0
Port B	PB15	PB14	PB13 (5V)	PB12 (5V)	PB11 (5V)	-	-	-	-	-	-	-	-	-	-	-
Port C	-	-	-	-	PC11 (5V)	PC10 (5V)	PC9 (5V)	PC8 (5V)	PC7 (5V)	-	-	-	-	-	-	-
Port D	PD15 (5V)	PD14 (5V)	PD13 (5V)	PD12 (5V)	PD11 (5V)	PD10 (5V)	PD9 (5V)	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	PF4 (5V)	PF3 (5V)	PF2 (5V)	PF1 (5V)	PF0 (5V)

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PB13, PB12, PB11, PD15, PD14, and PD13 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
4	PF3	BUSAY BUSBX	TIM0_CC0 #27 TIM0_CC1 #26 TIM0_CC2 #25 TIM0_CDTI0 #24 TIM0_CDTI1 #23 TIM0_CDTI2 #22 TIM1_CC0 #27 TIM1_CC1 #26 TIM1_CC2 #25 TIM1_CC3 #24 LETIM0_OUT0 #27 LETIM0_OUT1 #26 PCNT0_S0IN #27 PCNT0_S1IN #26	US0_TX #27 US0_RX #26 US0_CLK #25 US0_CS #24 US0_CTS #23 US0_RTS #22 US1_TX #27 US1_RX #26 US1_CLK #25 US1_CS #24 US1_CTS #23 US1_RTS #22 LEU0_TX #27 LEU0_RX #26 I2C0_SDA #27 I2C0_SCL #26	CMU_CLK1 #6 PRS_CH0 #3 PRS_CH1 #2 PRS_CH2 #1 PRS_CH3 #0 ACMP0_O #27 ACMP1_O #27 DBG_TDI #0
5	AVDD	Analog power supply .			
6	HFXTAL_N	High Frequency Crystal input pin.			
7	HFXTAL_P	High Frequency Crystal output pin.			
8	RESETn	Reset input, active low.To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
9	NC	No Connect.			
10	PD9	BUSCY BUSDX	TIM0_CC0 #17 TIM0_CC1 #16 TIM0_CC2 #15 TIM0_CDTI0 #14 TIM0_CDTI1 #13 TIM0_CDTI2 #12 TIM1_CC0 #17 TIM1_CC1 #16 TIM1_CC2 #15 TIM1_CC3 #14 LETIM0_OUT0 #17 LETIM0_OUT1 #16 PCNT0_S0IN #17 PCNT0_S1IN #16	US0_TX #17 US0_RX #16 US0_CLK #15 US0_CS #14 US0_CTS #13 US0_RTS #12 US1_TX #17 US1_RX #16 US1_CLK #15 US1_CS #14 US1_CTS #13 US1_RTS #12 LEU0_TX #17 LEU0_RX #16 I2C0_SDA #17 I2C0_SCL #16	CMU_CLK0 #4 PRS_CH3 #8 PRS_CH4 #0 PRS_CH5 #6 PRS_CH6 #11 ACMP0_O #17 ACMP1_O #17
11	PD10	BUSCX BUSDY	TIM0_CC0 #18 TIM0_CC1 #17 TIM0_CC2 #16 TIM0_CDTI0 #15 TIM0_CDTI1 #14 TIM0_CDTI2 #13 TIM1_CC0 #18 TIM1_CC1 #17 TIM1_CC2 #16 TIM1_CC3 #15 LETIM0_OUT0 #18 LETIM0_OUT1 #17 PCNT0_S0IN #18 PCNT0_S1IN #17	US0_TX #18 US0_RX #17 US0_CLK #16 US0_CS #15 US0_CTS #14 US0_RTS #13 US1_TX #18 US1_RX #17 US1_CLK #16 US1_CS #15 US1_CTS #14 US1_RTS #13 LEU0_TX #18 LEU0_RX #17 I2C0_SDA #18 I2C0_SCL #17	CMU_CLK1 #4 PRS_CH3 #9 PRS_CH4 #1 PRS_CH5 #0 PRS_CH6 #12 ACMP0_O #18 ACMP1_O #18

Alternate	LOCATION								
Functionality	**0 - 3**	**4 - 7**	**8 - 11**	**12 - 15**	**16 - 19**	**20 - 23**	**24 - 27**	**28 - 31**	**Description**
TIM0_CC2	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11 15: PD9	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 14: PD9 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	Timer 0 Complimentary Dead Time Insertion channel 0.
TIM0_CDTI1	0: PA4 1: PA5 2: PB11 3: PB12	4: PB13 5: PB14 6: PB15 7: PC6	8: PC7 9: PC8 10: PC9 11: PC10	12: PC11 13: PD9 14: PD10 15: PD11	16: PD12 17: PD13 18: PD14 19: PD15	20: PF0 21: PF1 22: PF2 23: PF3	24: PF4 25: PF5 26: PF6 27: PF7	28: PA0 29: PA1 30: PA2 31: PA3	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2	0: PA5 1: PB11 2: PB12 3: PB13	4: PB14 5: PB15 6: PC6 7: PC7	8: PC8 9: PC9 10: PC10 11: PC11	12: PD9 13: PD10 14: PD11 15: PD12	16: PD13 17: PD14 18: PD15 19: PF0	20: PF1 21: PF2 22: PF3 23: PF4	24: PF5 25: PF6 26: PF7 27: PA0	28: PA1 29: PA2 30: PA3 31: PA4	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11 15: PD9	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	Timer 1 Capture Compare input / output channel 2.
TIM1_CC3	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 14: PD9 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	Timer 1 Capture Compare input / output channel 3.
US0_CLK	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11 15: PD9	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	USART0 clock input / output.
US0_CS	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 14: PD9 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	USART0 chip select input / output.
US0_CTS	0: PA4 1: PA5 2: PB11 3: PB12	4: PB13 5: PB14 6: PB15 7: PC6	8: PC7 9: PC8 10: PC9 11: PC10	12: PC11 13: PD9 14: PD10 15: PD11	16: PD12 17: PD13 18: PD14 19: PD15	20: PF0 21: PF1 22: PF2 23: PF3	24: PF4 25: PF5 26: PF6 27: PF7	28: PA0 29: PA1 30: PA2 31: PA3	USART0 Clear To Send hardware flow control input.
US0_RTS	0: PA5 1: PB11 2: PB12 3: PB13	4: PB14 5: PB15 6: PC6 7: PC7	8: PC8 9: PC9 10: PC10 11: PC11	12: PD9 13: PD10 14: PD11 15: PD12	16: PD13 17: PD14 18: PD15 19: PF0	20: PF1 21: PF2 22: PF3 23: PF4	24: PF5 25: PF6 26: PF7 27: PA0	28: PA1 29: PA2 30: PA3 31: PA4	USART0 Request To Send hardware flow control output.

7.3 QFN48 Package Marking

Figure 7.3. QFN48 Package Marking

The package marking consists of:

- PPPPPPPPP – The part number designation.
- TTTTTT – A trace or manufacturing code. The first letter is the device revision.
- YY – The last 2 digits of the assembly year.
- WW – The 2-digit workweek when the device was assembled.
- # – Reserved for future use. Current value is 0.

Table 8.1. QFN32 Package Dimensions

Dimension	Min	Typ	Max
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3		0.20 REF	
b	0.18	0.25	0.30
D/E	4.90	5.00	5.10
D2/E2	3.40	3.50	3.60
E		0.50 BSC	
L	0.30	0.40	0.50
K	0.20	—	—
R	0.09	—	0.14
aaa		0.15	
bbb		0.10	
ccc		0.10	
ddd		0.05	
eee		0.08	
fff		0.10	

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220, Variation VKKD-4.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Table 8.2. QFN32 PCB Land Pattern Dimensions

Dimension	Typ
S1	4.01
S	4.01
L1	3.50
W1	3.50
e	0.50
W	0.26
L	0.86

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.
4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
5. The stencil thickness should be 0.125 mm (5 mils).
6. The ratio of stencil aperture to land pad size can be 1:1 for all perimeter pads.
7. A 3x3 array of 0.85 mm square openings on a 1.00 mm pitch can be used for the center ground pad.
8. A No-Clean, Type-3 solder paste is recommended.
9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

9. Revision History

9.1 Revision 1.1

2016-Oct-26

- System Overview Sections: Minor wording and typographical error fixes.
- Electrical Characteristics: Minor wording and typographical error fixes.
- "HFRCO and AUXHFRCO" table in Electrical Characteristics: f_HFRCO symbol changed to f_HFRCO_ACC.
- Pinout tables: APORT channel details removed from "Analog" column. This information is now found in the APORT client map sections.
- Updated APORT client map sections.

9.2 Revision 1.0

2016-Jul-22

- Electrical Characteristics: Minimum and maximum value statement changed to cover full operating temperature range.
- Finalized Specification Tables. Tables with condition/min/typ/max or footnote changes include:
  - Absolute Maximum Ratings
  - General Operating Conditions
  - DC-DC Converter
  - LFRCO
  - HFRCO and AUXHFRCO
  - ADC
  - IDAC
- Updated Typical Performance Graphs.
- Added note for 5V tolerance to pinout GPIO Overview sections.
- Updated OPN decoder with latest revision.
- Updated Package Marking text with latest descriptions.

9.3 Revision 0.95

2016-04-11

- All OPNs changed to rev C0.
- Electrical specification tables updated with latest characterization data and production test limits.

9.4 Revision 0.31

- Engineering samples note added to ordering information table.

9.5 Revision 0.3

- Re-formatted ordering information table and OPN decoder.
- Removed extraneous sections from dc-dc from system overview.
- Updated table formatting for electrical specifications.
- Updated electrical specifications with latest available data.
- Added I2C and USART SPI timing tables.
- Moved dc-dc graph to typical performance curves.
- Updated APORT tables and APORT references to correct nomenclature.
- Updated top marking description.

9.6 Revision 0.2

Updated ordering table.

Changed "1.62 V to 3.8 V Single Power Supply" to "1.62 V to 3.8 V Power Supply" in the Feature List.